

ABSTRACT

The present invention includes a semiconductor package that forms the array solder joints on the die surface and corresponding BGA substrate and PCB respectively. The life times of array solder joints are increased through the
5 use of two sets of array joints. The top array comprises a plurality of high melting solder joints, while the bottom array comprises a plurality of high melting solder joints and low melting solder paste. The reflow temperature of SMT assembly is between the aforementioned high melting solder joints and low melting solder paste. In addition, each solder joint comprises a flat
10 surface at its front edge.